

## AMENDMENTS TO THE ABSTRACT

Please replace the Abstract with the following amended paragraph marked up to show changes made relative to the immediate prior version:

A system may include a pre-formed portion of underfill material defining openings. The openings may be configured to pass electrical interconnects for coupling an integrated circuit die to a portion of a substrate. In some aspects, the pre-formed portion of underfill is coupled to a substrate having the electrical interconnects formed thereon.